	Spec. No.: Date:	FCCR-K-HTS-0001 /5 2017. 1. 10
Title: CHIP FUSE; RECTANGL	ILAR TYPE	
Style: FCCR10,16		
RoHS COMPLIAN Halogen and Antir	-	
Product specification contained in this s are subject to change at any time withou If you have any questions or a Purchasi Agreement is necessary, please contact	ut notice ng Specification	
Note: Stock conditions Temperature: +5°C ~ +35°C Relative humidity: 25% ~ 75% The period of guarantee: Within 2 year from shipmen t by Solderability shall be satisfied.	ŀ	жатара со

Title: CHIP FUSES; RECTANGULAR TYPE FCCR10,16

Page: 1/9

1. Scope

- 1.1 This specification covers the detail requirements for chip fuses; rectangular type, style of FCCR10,16.
- 1.2 Applicable documents

UL248–1–2000 Low–Voltage Fuses–Part1: General Requirements UL248–14–2000 Low–Voltage Fuses–Part14: Supplemental Fuses CSA C22.2 No.248.1–2000 Low–Voltage Fuses–Part1: General Requirements CSA C22.2 No.248.14–2000 Low–Voltage Fuses–Part14: Supplemental Fuses IEC60127–1 Miniature fuses–part 1: Definitions for miniature fuses and general requirements for miniature fuse–links IEC60127–4 Miniature fuses–Part4: Universal modular fuse–links (UMF)

2. Classification

Type designation shall be the following form.



5 Packaging form

В	Bulk (loose package)
PA	Press pocket taping
TP	Paper taping

3. Safety standard approval

• UL248-1 and UL248-14

• CSA C22.2, No. 248.1–00 and CSA C22.2, No. 248.14–00 The file number to be designated by UL and C–UL shall be as follows: E176847

CHIP FUSES; RECTANGULAR TYPE Title: FCCR10,16

Drawing No: FCCR-K-HTS-0001 /5

> Page: 2/9

4. Rating

4.1 The ratings shall be in accordance with Table-1.

	U I			Table	⊢1			
	Rated current		Internal Rated		Breaking	Time / current characteristic		
Style	Symbol	(A)	Marking symbol	resistance value (mΩ max.)	voltage (V)	capacity (A)	Current	Pre-arcing time
	151	0.15	$\overline{0}$	1850				
	201	0.2	Z	1250				
FCCR10	251	0.25	С	880	DC24	35	200%	5 s max.
	321	0.315	D	600	DC24		20070	5 5 max.
	401	0.4	E	400				
	501	0.5	F	300				
	151	0.15	OB	2300			200%	5 s max.
	201	0.2	ZB	1350				
	251	0.25	CB	1000				
	321	0.315	DB	600				
	401	0.4	EB	450				
	501	0.5	FB	300				
	631	0.63	IB	220				
FCCR16	751	0.75	AB	190	DC50	50		
	801	0.8	KB	165				
	102	1.0	LB	130				
	132	1.25	MB	110				
	152	1.5	HB	90				
	162	1.6	NB	75				
	202	2.0	SB	65				
	252	2.5	TB	40				

4.2 Working temperature range: -55 to +125(°C)

5. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table_2

S	Symbol	Packaging form		Standard packaging quantity / units	Application			
	В	Bulk (loose package)		1,000 pcs.	FCCR10,16			
	PA	Press pocket taping (paper taping)	8mm width, 2mm pitches	10,000 pcs.	FCCR10			
	TP	Paper taping	8mm width, 4mm pitches	5,000 pcs.	FCCR16			

Product specification contained in this specification are subject to change at any time without notice. If you have any questions or a Purchasing Specification for any quality agreement is necessary, please contact our sales staff. Issue: KAMAYA ELECTRIC CO., LTD. Research & Development Department HOKKAIDO Research center Last update: 2017.1.10

Title: CHIP FUSES; RECTANGULAR TYPE FCCR10,16

Page: 3/9

6. Dimensions

6.1 The resistor shall be of the design and physical dimensions in accordance with Figure-1 and Table-3.



Figure-1

Table-3 Unit:mm L W Н d Style С FCCR10 1.0±0.05 0.5±0.05 0.25±0.10 0.4±0.05 0.2±0.1 0.8 +0.15 FCCR16 1.6±0.1 0.45±0.10 0.3±0.15 0.3±0.1

6.2 Net weight (Reference)

Style	Net weight(mg)
FCCR10	0.8
FCCR16	2

7. Marking

The Marking symbol of Sub- clause 4.1 shall be marked on over coat side.

(Example)

Style	Optional code	Marking symbol	Content
FCCR10	AB	Z	FCCR10 201 AB
FCCR16	AB	EB	FCCR16 401 AB

Title: CHIP FUSES; RECTANGULAR TYPE FCCR10,16

Page:

4/9

8. Performance

8.1 Unless otherwise specified, the standard range of atmospheric conditions for tests is as follows; Ambient temperature: 5 °C to 35 °C, Relative humidity: 45 % to 85 %, Air presser: 86 kPa to 106 kPa If there is any doubt the results, measurements shall be made within the following:

Ambient temperature: 20 °C \pm 2 °C, Relative humidity: 60 % to 70 %, Air presser: 86 kPa to 106 kPa 8.2 The performance shall be satisfied in Table–4.

		Table-4(1)			
No.	Test items	Condition of test	Perfo	ormance re	quirements
1	Temperature rise	The fuse shall be mounted on the test substrate as shown in Figure–2. Measurement temp.: 10 °C to 30 °C Test current: Rated current The temperature at the hottest point on the surface of the fuse shall be measured after temperature equilibrium has been attained.	eof		
2	Current carrying capacity	The fuse shall be mounted on the test substrate as shown in Figure–2. Test current: 110 % of Rated current Test temp.: 70 °C \pm 2 °C Test period: 1h	Without opening		
3	Time / current characteristic	The fuse shall be mounted on the test substrate as shown in Figure–2. Test current shall be applied for continuously.	Optional code AB	Current 200%	Pre-arcing time 5 s max.
4	Terminal bond strength of the face plating	JIS C 60068-2-21 Ue1 The fuse shall be mounted on the test substrate as shown in Figure–2. Bending value: 3 mm (Among the fulcrums: 90 mm) Duration: 10 s \pm 1 s	±10% No evi		
5	Resistance to soldering heat	 Test by a piece. Temp. of solder bath: 260 °C ± 5 °C Immersion time: 10 s ± 1 s After immersion into solder, leaving the room temp. for 1h or more, and then measure the internal resistance. Reflow soldering Pre-heating: 150 °C ~ 180 °C, 120 s max. Peak: 260 °C ± 5 °C, 10 s max. Refrow cycle: 2 times After immersion into solder, leaving the room temp. for 1h or more, and then measure the internal resistance. 	±10% No evi damage	of internal r	fappearance
6	Solderability	JIS C 60068-2-58 Test by a piece Flux: Rosin–Methanol Temp. of solder: bath: 235 °C ± 5 °C Immersion time: 2 s ± 0.5 s		f 95 % cov	al immersed shall ered with a new

Product specification contained in this specification are subject to change at any time without notice.

If you have any questions or a Purchasing Specification for any quality agreement is necessary, please contact our sales staff.

Issue: KAMAYA ELECTRIC CO., LTD. Research & Development Department HOKKAIDO Research center Last update: 2017.1.10

Drawing No: FCCR–K–HTS–0001 /5

Title: CHIP FUSES; RECTANGULAR TYPE

FCCR10,16

Page: 5/9

	Table-4(2)					
No.	Test items	Condition of test	Performance requirements			
7	Rapid change temperature	JIS C 60068-2-14 Na	Change of internal resistance:			
		The fuse shall be mounted on the test substrate as	±10%			
		shown in Figure–2.	No evidence of appearance			
		Upper temperature: +125 °C	damage			
		Lower temperature: -55 °C				
		Duration of exposure at each temperature: 30 min.				
		Number of cycles: 5 cycles				
8	Endurance test	The fuse shall be mounted on the test substrate as	The voltage drop across the fuse			
		shown in Figure–2.	after the test shall not have			
		Test condition: Nominal ambient temp. and Relative	increased by more than 10 % of			
		humidity.	the value measured before test.			
		Test potential:				
		1. Cycle of 1 h "ON" and 15 min. "OFF" at 1.05 times				
		rated current for 100 cycles.				
1		2. After above the test, 1.25 times rated current for				
		1h.				

9. Test substrate



Remark 1). Material: Epoxide woven glass Thickness: 1. 6mm Thickness of copper clad: 0. 035mm

Product specification contained in this specification are subject to change at any time without notice. If you have any questions or a Purchasing Specification for any quality agreement is necessary, please contact our sales staff. Issue: KAMAYA ELECTRIC CO., LTD. Research & Development Department HOKKAIDO Research center Last update: 2017.1.10

Title: CHIP FUSES; RECTANGULAR TYPE FCCR10,16

Page: 6/9

10. Taping

10.1 Applicable documents JIS C 0806–3: 2014, EIAJ ET–7200C: 2010

10.2 Taping dimensions

10.2.1 Press pocket taping(8mm width, 2mm pitches)

Taping dimensions shall be in accordance with Figure-3 and Table-5.



10.2.2 Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-4 and Table-6.



	1	rigure-4				
Table–6 Unit:mm						
Style	А	В	t 1	t 2		
FCCR16	1.15±0.15	1.9 <u>+</u> 0.2	0.6 <u>+</u> 0.1	0.8 max.		

Product specification contained in this specification are subject to change at any time without notice.

If you have any questions or a Purchasing Specification for any quality agreement is necessary, please contact our sales staff. Issue: KAMAYA ELECTRIC CO., LTD. Research & Development Department HOKKAIDO Research center Last update: 2017.1.10

Page: 7/9

- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following FCCR10:Figure-5,FCCR16: Figure-6.
- 6). When the tape is bent with the minimum radius for 25 mm, the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.
 - The maximum number of missing components shall be one or 0.1%, whichever is greater.
- 8). The fuses shall be faced to upward at the over coating side in the carrier cavity.



Title: CHIP FUSES; RECTANGULAR TYPE FCCR10,16

Page: 8/9

10.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure–5 and Table–6. Plastic reel (Based on EIAJ ET–7200C)



Note: Marking label shall be marked on a place of Marking A or two place of marking A and B.

10.4 Leader and trailer tape.



Figure-8

11. Marking on package

The label of a minimum package shall be legibly marked with follows.

11.1 Marking A

(1) Classification (Style, Rated current, Optional code, Packaging form) (2) Quantity (3) Lot number

(5) Manufacturer's name or trade mark (6) UL and /or C–UL recognized component mark (7) Others

11.2 Marking B (KAMAYA Control label)

Product specification contained in this specification are subject to change at any time without notice.

If you have any questions or a Purchasing Specification for any quality agreement is necessary, please contact our sales staff. Issue: KAMAYA ELECTRIC CO., LTD. Research & Development Department HOKKAIDO Research center Last update: 2017.1.10

Title: CHIP FUSES; RECTANGULAR TYPE FCCR10,16

Page: 9/9

- 12. Recommended Derating for Rated Current
 - •Nominal Derating

Option Code AB: Nominal Derating \leq 75% of Rated Current

•Temperature Derating

Please refer to the following graph regarding the current derating value for ambient temperature.



Ex.) • If Optional code: AB (Rated Current:0.5A) is used under ambient temperature 70°C Kamaya recommends, less than the current value derated as below, Rated Current: 0.5A× (Nominal Derating : 75% × Temperature Derating : 100%) =0.375A

Product specification contained in this specification are subject to change at any time without notice. If you have any questions or a Purchasing Specification for any quality agreement is necessary, please contact our sales staff. Issue: KAMAYA ELECTRIC CO., LTD. Research & Development Department HOKKAIDO Research center Last update: 2017.1.10